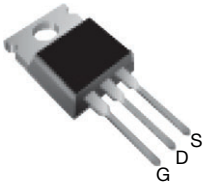
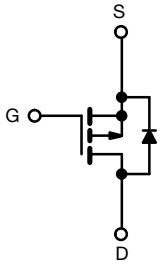
# Power MOSFET

TO-220AB




P-Channel MOSFET

## FEATURES

- Dynamic dV/dt rating
- P-channel
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Available

RoHS* Available

**Note**

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

## DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

| PRODUCT SUMMARY | | |
|---|---|---|
| $V_{DS}$ (V) | -200 | |
| $R_{DS(on)}$ (Ω) | $V_{GS}$ = -10 V | 1.5 |
| $Q_g$ max. (nC) | 22 | |
| $Q_{gs}$ (nC) | 12 | |
| $Q_{gd}$ (nC) | 10 | |
| Configuration | Single | |

| ORDERING INFORMATION | |
|---|---|
| Package | TO-220AB |
| Lead (Pb)-free | IRF9620PbF |
| Lead (Pb)-free and halogen-free | IRF9620PbF-BE3 |

| ABSOLUTE MAXIMUM RATINGS ($T_C$ = 25 °C, unless otherwise noted) | | | | | |
|---|---|---|---|---|---|
| PARAMETER | | | SYMBOL | LIMIT | UNIT |
| Drain-source voltage | | | $V_{DS}$ | -200 | V |
| Gate-source voltage | | | $V_{GS}$ | ± 20 | |
| Continuous drain current | $V_{GS}$ at -10 V | $T_C$ = 25 °C | $I_D$ | -3.5 | A |
| | | $T_C$ = 100 °C | | -2.0 | |
| Pulsed srain current [a] | | | $I_{DM}$ | -14 | |
| Linear serating factor | | | | 0.32 | W/°C |
| Maximum power dissipation | $T_C$ = 25 °C | | $P_D$ | 40 | W |
| Peak diode recovery dV/dt [b] | | | dV/dt | -5.0 | V/ns |
| Operating junction and storage temperature range | | | $T_J$, $T_{stg}$ | -55 to +150 | °C |
| Soldering recommendations (peak temperature) [c] | For 10 s | | | 300 | |
| Mounting torque | 6-32 or M3 screw | | | 10 | lbf · in |
| | | | | 1.1 | N · m |

**Notes**

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. $I_{SD}$ ≤ -3.5 A, dI/dt ≤ 95 A/µs, $V_{DD}$ ≤ $V_{DS}$, $T_J$ ≤ 150 °C

c. 1.6 mm from case

| THERMAL RESISTANCE RATINGS | | | | |
|---|---|---|---|---|
| **PARAMETER** | **SYMBOL** | **TYP.** | **MAX.** | **UNIT** |
| Maximum junction-to-ambient | $R_{thJA}$ | - | 62 | °C/W |
| Case-to-sink, flat, greased surface | $R_{thCS}$ | 0.50 | - | |
| Maximum junction-to-case (drain) | $R_{thJC}$ | - | 3.1 | |

| **SPECIFICATIONS** ($T_J$ = 25 °C, unless otherwise noted) | | | | | | |
|---|---|---|---|---|---|---|
| **PARAMETER** | **SYMBOL** | **TEST CONDITIONS** | **MIN.** | **TYP.** | **MAX.** | **UNIT** |
| **Static** | | | | | | |
| Drain-source breakdown voltage | $V_{DS}$ | $V_{GS}$ = 0 V, $I_D$ = -250 µA | -200 | - | - | V |
| $V_{DS}$ temperature coefficient | $\Delta V_{DS}/T_J$ | Reference to 25 °C, $I_D$ = -1 mA | - | -0.22 | - | V/°C |
| Gate-source threshold voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$, $I_D$ = -250 µA | -2.0 | - | -4.0 | V |
| Gate-source leakage | $I_{GSS}$ | $V_{GS}$ = ± 20 V | - | - | ± 100 | nA |
| Zero gate voltage drain current | $I_{DSS}$ | $V_{DS}$ = -200 V, $V_{GS}$ = 0 V | - | - | -100 | µA |
| | | $V_{DS}$ = -160 V, $V_{GS}$ = 0 V, $T_J$ = 125 °C | - | - | -500 | |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}$ = -10 V; $I_D$ = -1.5 A [b] | - | - | 1.5 | Ω |
| Forward transconductance | $g_{fs}$ | $V_{DS}$ = -50 V, $I_D$ = -1.5 A [b] | 1.0 | - | - | S |
| **Dynamic** | | | | | | |
| Input capacitance | $C_{iss}$ | $V_{GS}$ = 0 V, $V_{DS}$ = -25 V, f = 1.0 MHz, see fig. 5 | - | 350 | - | pF |
| Output capacitance | $C_{oss}$ | | - | 100 | - | |
| Reverse transfer capacitance | $C_{rss}$ | | - | 30 | - | |
| Total gate charge | $Q_g$ | $V_{GS}$ = -10 V; $I_D$ = -4.0 A, $V_{DS}$ = -160 V, see fig. 11 and 18 [b] | - | - | 22 | nC |
| Gate-source charge | $Q_{gs}$ | | - | - | 12 | |
| Gate-drain charge | $Q_{gd}$ | | - | - | 10 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}$ = -100 V, $I_D$ = -1.5 A, $R_g$ = 50 Ω, $R_D$ = 67 Ω, see fig. 17 [b] | - | 15 | - | ns |
| Rise time | $t_r$ | | - | 25 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 20 | - | |
| Fall time | $t_f$ | | - | 15 | - | |
| Gate input resistance | $R_g$ | f = 1 MHz, open drain | 0.9 | - | 5.7 | Ω |
| Internal drain inductance | $L_D$ | Between lead, 6 mm (0.25") from package and center of die contact  | - | 4.5 | - | nH |
| Internal source inductance | $L_S$ | | - | 7.5 | - | |
| **Drain-Source Body Diode Characteristics** | | | | | | |
| Continuous source-drain diode current | $I_S$ | MOSFET symbol showing the integral reverse p - n junction diode  | - | - | -3.5 | A |
| Pulsed diode forward current [a] | $I_{SM}$ | | - | - | -14 | |
| Body diode voltage | $V_{SD}$ | $T_J$ = 25 °C, $I_S$ = -3.5 A, $V_{GS}$ = 0 V [b] | - | - | -7.0 | V |
| Body diode reverse recovery time | $t_{rr}$ | $T_J$ = 25 °C, $I_F$ = -3.5 A, dI/dt = 100 A/µs [b] | - | 300 | 450 | ns |
| Body diode reverse recovery charge | $Q_{rr}$ | | - | 1.9 | 2.9 | µC |
| Forward turn-on time | $t_{on}$ | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$) | | | | |

**Notes**

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

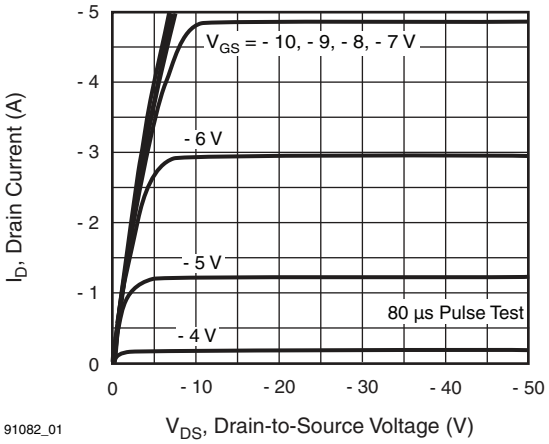



**Fig. 1 - Typical Output Characteristics**

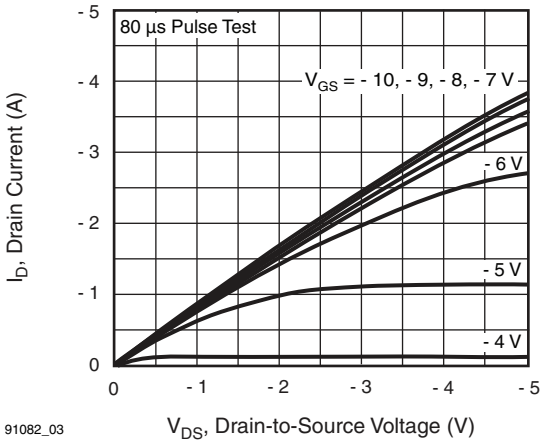



**Fig. 3 - Typical Saturation Characteristics**

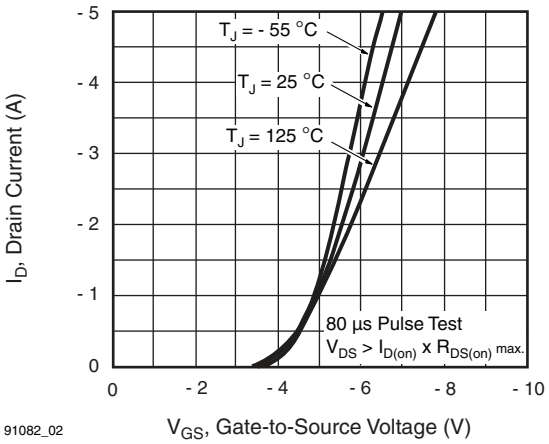



**Fig. 2 - Typical Transfer Characteristics**

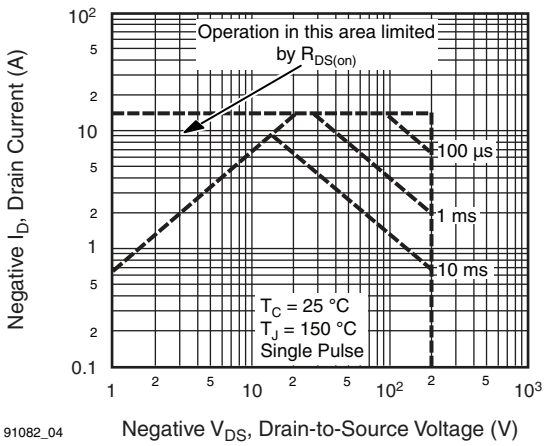



**Fig. 4 - Maximum Safe Operating Area**

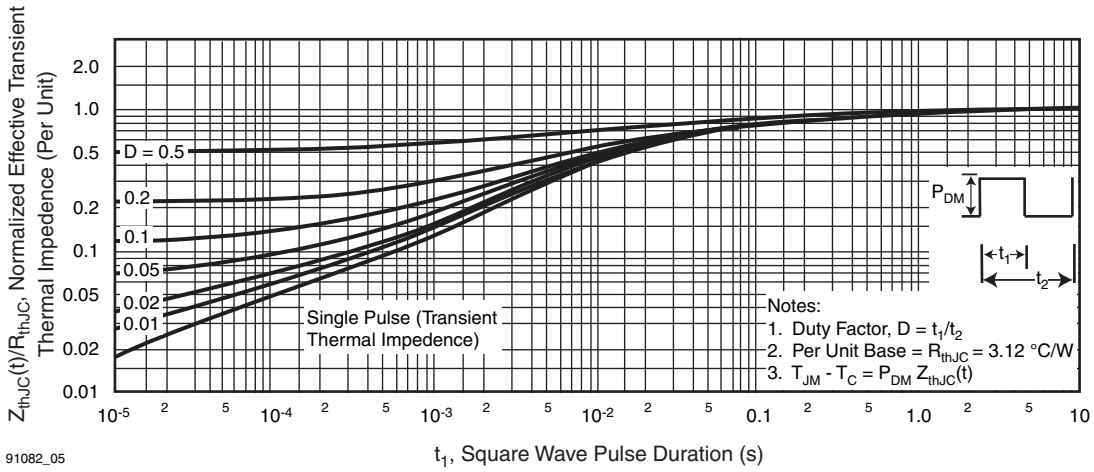



**Fig. 5 - Maximum Effective Transient Thermal Impedance, Junction-to-Case vs. Pulse Duration**

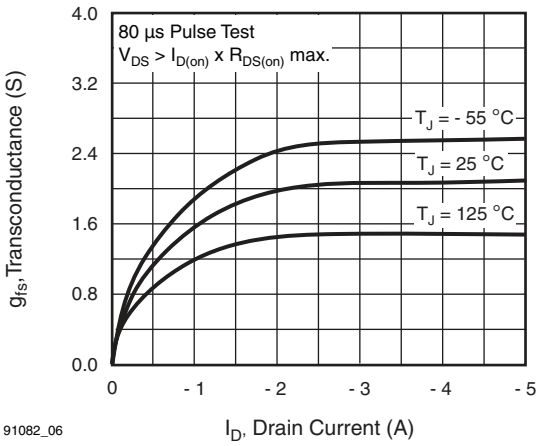



Fig. 6 - Typical Transconductance vs. Drain Current

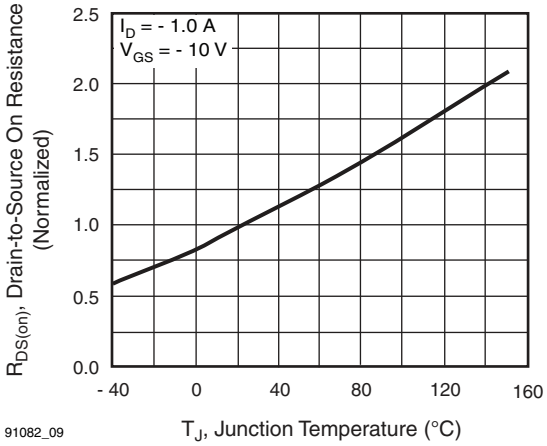



Fig. 9 - Normalized On-Resistance vs. Temperature

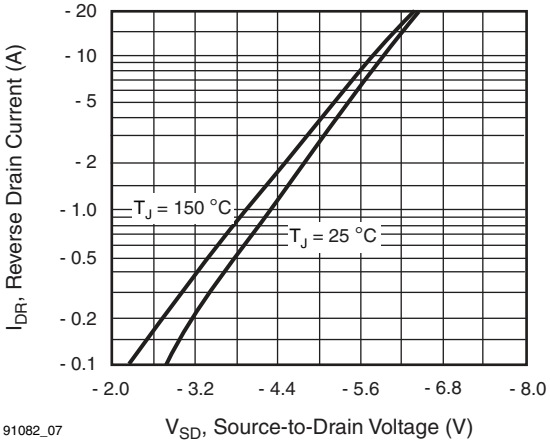



Fig. 7 - Typical Source-Drain Diode Forward Voltage

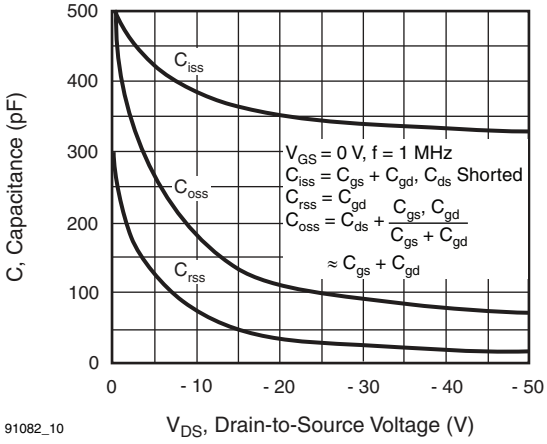



Fig. 10 - Typical Capacitance vs. Drain-to-Source Voltage

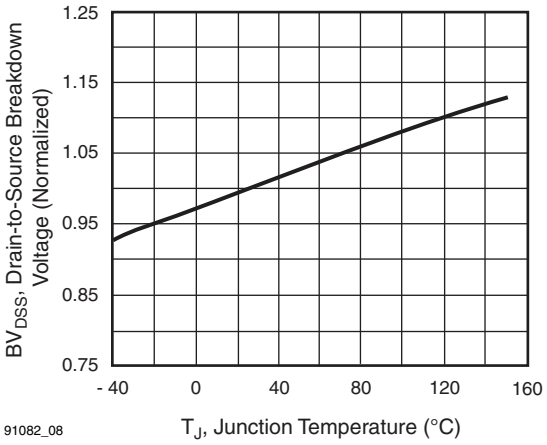



Fig. 8 - Breakdown Voltage vs. Temperature

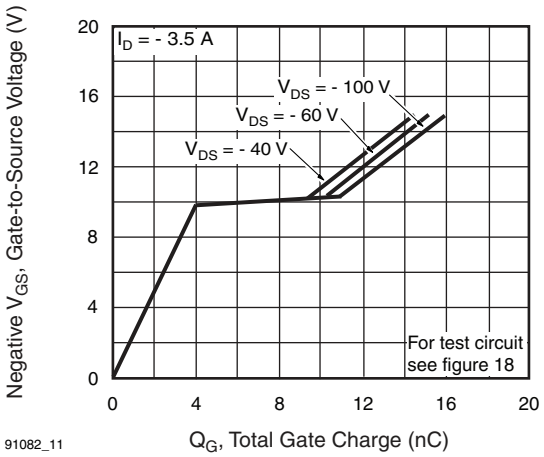



Fig. 11 - Typical Gate Charge vs. Gate-to-Source Voltage

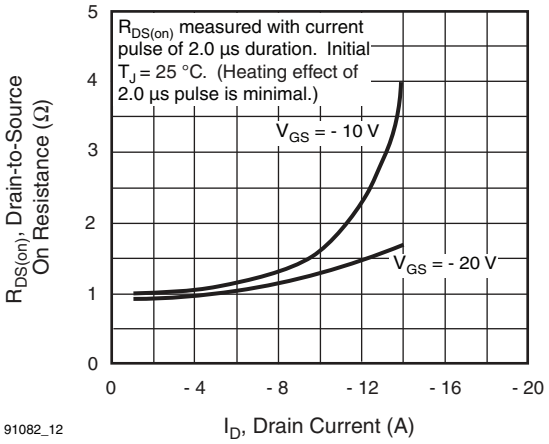



**Fig. 12 - Typical On-Resistance vs. Drain Current**

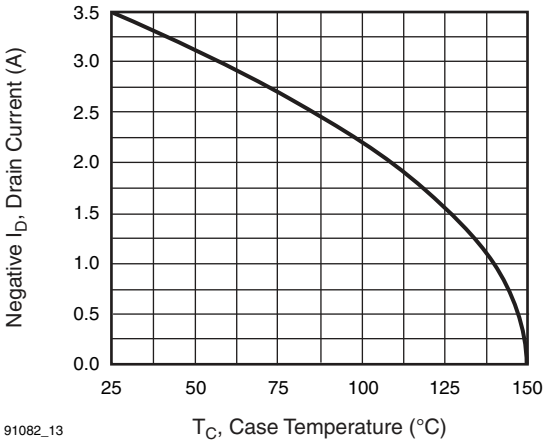



**Fig. 13 - Maximum Drain Current vs. Case Temperature**

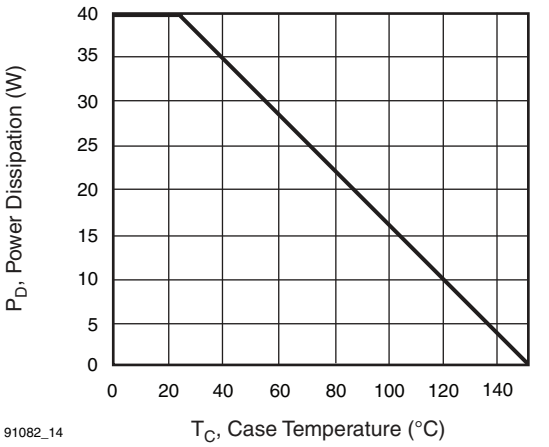



**Fig. 14 - Power vs. Temperature Derating Curve**

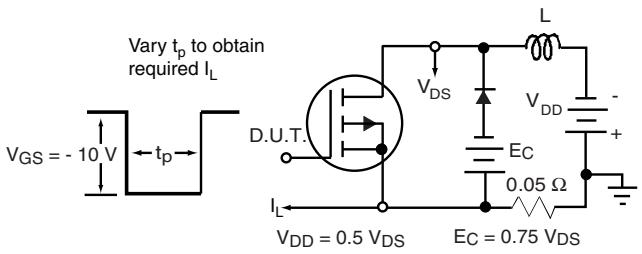



**Fig. 15 - Clamped Inductive Test Circuit**

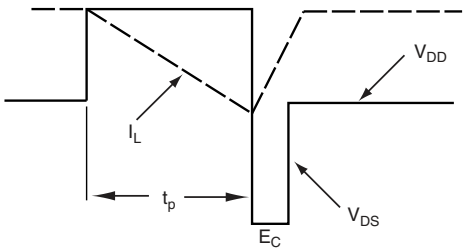



**Fig. 16 - Clamped Inductive Waveforms**

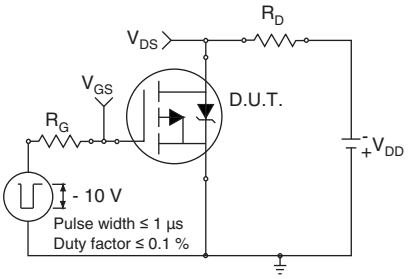



**Fig. 17a - Switching Time Test Circuit**

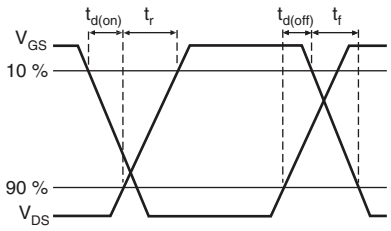



**Fig. 17b - Switching Time Waveforms**

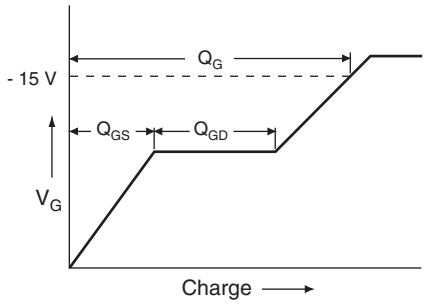



**Fig. 18a - Basic Gate Charge Waveform**

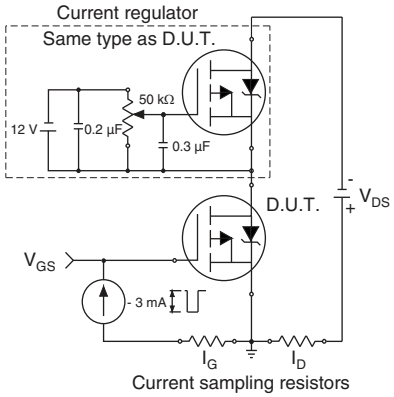
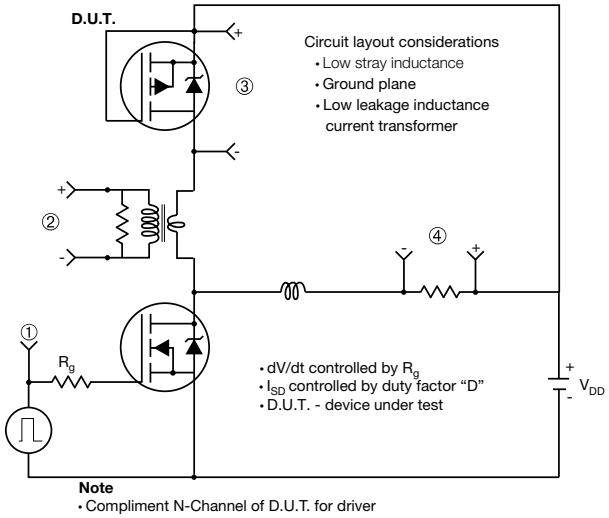



**Fig. 18b - Gate Charge Test Circuit**

**Peak Diode Recovery dV/dt Test Circuit**



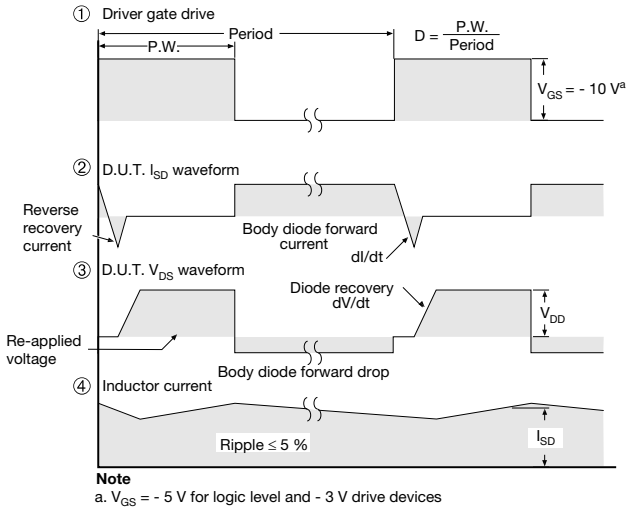
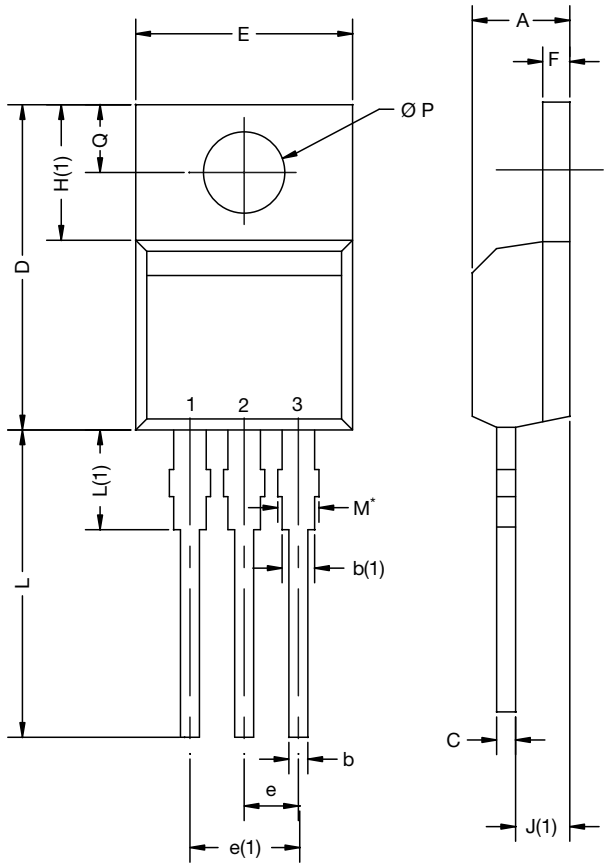




**Fig. 19 - For P-Channel**

*Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91082.*

# TO-220-1




| DIM. | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.24 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.02 | 0.027 | 0.040 |
| b(1) | 1.14 | 1.78 | 0.045 | 0.070 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.33 | 15.85 | 0.564 | 0.624 |
| E | 9.96 | 10.52 | 0.392 | 0.414 |
| e | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.10 | 6.71 | 0.240 | 0.264 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.36 | 14.40 | 0.526 | 0.567 |
| L(1) | 3.33 | 4.04 | 0.131 | 0.159 |
| Ø P | 3.53 | 3.94 | 0.139 | 0.155 |
| Q | 2.54 | 3.00 | 0.100 | 0.118 |
| ECN: E21-0621-Rev. D, 04-Nov-2021<br>DWG: 6031 | | | | |

**Note**

- M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

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